

ETP01-xx21

Protection for Ethernet lines

Features

- Differential and common mode protection
- Telcordia GR1089 Intrabuilding: 100 A, 2/10 μs
- ITU-T K20/21: 37.5 A, 5/310 μs
- Low capacitance: 13 pF max at 0 V
- UL94 V0 approved resin
- SO8 package is JEDEC registered

Benefits

- Trisil[™] technology is not subject to ageing and provides a fail safe mode in short circuit for a better protection.
- This series is used to help equipment to meet main standards such as UL61950, IEC950 / CSA C22.2 and UL1459.

Complies with the following standards

- IEC 61000-4-2: Level 4
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883E-Method 3015-7: class3:
 25 kV (Human body model)
- TELCORDIA GR-1089 Core: 100 A, 2/10 μs
- ITU-T K20/21: 37.5 A, 5/310 μs
- IEC 61000-4-5: 2 kV, 42 Ω, 48 A, 8/20 µs

Applications

This series can meet subscriber and central office requirements.

- Protection against telecommunications surge standards on:
 - 10/100 Mbps Ethernet
 - Ethernet Gigabit
 - T1 / E1 line cards

TM: Trisil is a trademark of STMicroelectronics

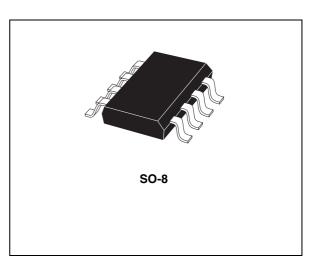
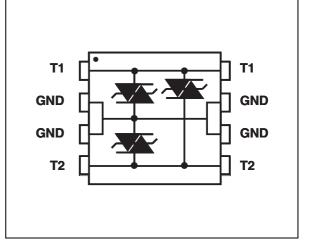


Figure 1. Schematic diagram



Description

The ETP01 series is a low capacitance transient surge arrestor designed for protection of high debit rate communication network. Planar technology used combines a high surge capability to comply with Telcordia GR1089 Intrabuilding and ITU-T K20/21, and low capacitance to avoid distortion of high speed signals such as Ethernet.

1 Characteristics

Symbol	Parameter	Value	Unit	
I _{pp}		5/310 µs	37.5	Α
	Peak pulse current ⁽¹⁾	8/20 μs	48	Α
		2/10 µs	100	Α
I _{TSM}	Non repetitive surge peak on state current t = 20 ms		8	А
T _{stg} T _j	Storage temperature range Operating junction temperature range	-55 to 150 -40 to 150	°C	
ΤL	Maximum temperature for soldering during 10 s	260	°C	

Table 1. Absolute ratings $(T_{amb} = 25 \ ^{\circ}C)$

1. Surge capability tested according to ITU-T K20/21 and Telcordia GR1089 Intrabuilding connections (Metallic and Longitudinal tests).

Table 2. Electrical characteristics ($T_{amb} = 25 \ ^{\circ}C$)

	I _{RM} @ V _{RM}		I _{RM} @ V _{RM}		V _{bo}	Ι _Η	С	С
Order code	μA typ.	v	μA max.	v	V max.	mA min.	pF max. ⁽¹⁾	pF max. ⁽²⁾
ETP01-1621	0.01	3.3	1	16	25	30	16	13
ETP01-2821	0.01	3.3	1	28	36	30	16	13

1. Test conditions: Capacitance between I/O and GND, $V_R = 0$ V bias, $V_{RMS} = 1$ V, F = 1 MHz

2. Test conditions: Capacitance between I/O and I/O, V_{R} = 0 V bias, V_{RMS} = 1 V, F = 1 MHz



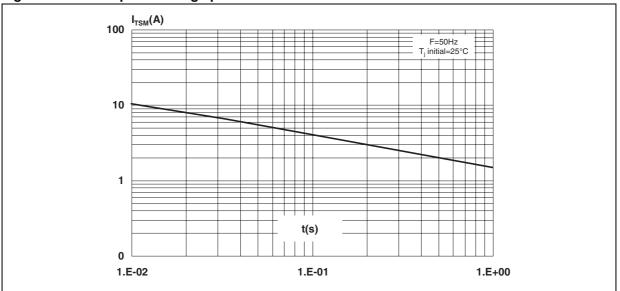
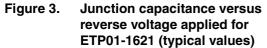
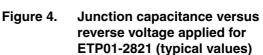
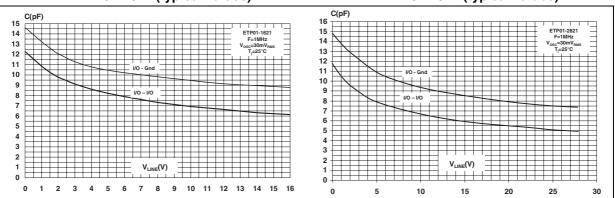


Figure 2. Non repetitive surge peak on-state current versus overload duration









2 Application information

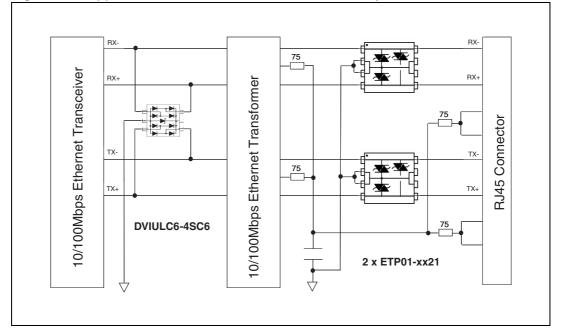
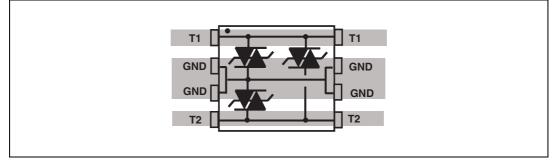


Figure 5. Application schematic for Ethernet 10/100 Mbps





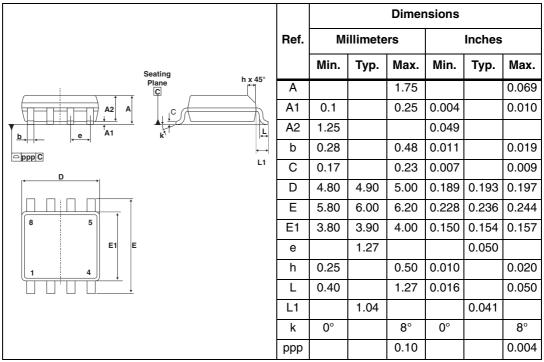


3 Package information

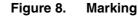
• Epoxy meets UL94, V0

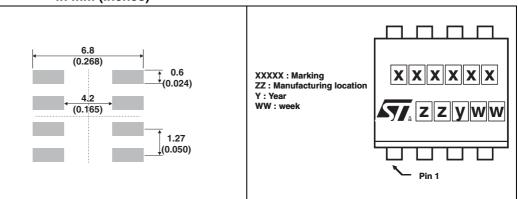
In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at *www.st.com*.

Table 3. SO-8 dimensions











4 Ordering information

Table 4.Ordering information

Order code	Marking	Weight	Base qty	Delivery mode
ETP01-162RL	ETP162	0.08 g	2500	Tape and reel
ETP01-282RL	ETP282	0.08 g	2500	Tape and reel

5 Revision history

Table 5.Document revision history

Date	Revision	Changes
04-Mar-2008	1	Initial release.

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